

# IRF140-143/IRF540-543 7-39-/3 N-Channel Power MOSFETs, 27 A, 60-100 V

Power And Discrete Division

### Description

These devices are n-channel, enhancement mode, power MOSFETs designed especially for high power, high speed applications, such as switching power supplies, UPS, AC and DC motor controls, relay and solenoid drivers and high energy pulse circuits.

- Low RDS(on)
- V<sub>GS</sub> Rated at ± 20 V
- Silicon Gate for Fast Switching Speeds
- I<sub>DSS</sub>, V<sub>DS(on)</sub>, Specified at Elevated Temperature
- Rugged
- Low Drive Requirements
- Ease of Paralleling

### TO-204AE



TO-220AB



IRF540 IRF541 IRF542 IRF543

IRF140 IRF141 IRF142 IRF143

## **Product Summary**

Part Number	V <sub>DSS</sub>	R <sub>DS (on)</sub>	I <sub>D</sub> at T <sub>C</sub> = 25°C	I <sub>D</sub> at T <sub>C</sub> = 100°C	Case Style
IRF140	100 V	0.085 Ω	27 A	17 A	TO-204AE
IRF141	60 V	0.085 Ω	27 A	17 A	
IRF142	100 V	0.11 Ω	24 A	15 A	
IRF143	60 V	0.11 Ω	24 A	15 A	
IRF540	100 V	0.085 Ω	27 A	17 A	TO-220AB
IRF541	60 V	0.085 Ω	27 A	17 A	
IRF542	100 V	0.11 Ω	24 A	15 A	
IRF543	60 V	0.11 Ω	24 A	15 A	
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#### Notes

For information concerning connection diagram and package outline, refer to Section 7.

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Symbol	Characteristic	Rating IRF140/142 IRF540/542	Rating IRF141/143 IRF541/543	Unit
V <sub>DSS</sub>	Drain to Source Voltage <sup>1</sup>	100	60	V
V <sub>DGR</sub>	Drain to Gate Voltage <sup>1</sup> $R_{GS} = 20 \text{ k}\Omega$	100	60	V
V <sub>GS</sub>	Gate to Source Voltage	± 20	± 20	
T <sub>J</sub> , T <sub>stg</sub>	Operating Junction and Storage Temperatures	-55 to +15C	-55 to +150	v
TL	Maximum Lead Temperature for Soldering Purposes, 1/8" From Case for 5 s	275	275	°C
laximum	Thermal Characteristics			
		IRF140-143	IRF540-543	
R <sub>∂JC</sub>	Thermal Resistance, Junction to Case	1.0	1.0	°C/W
P <sub>D</sub>	Total Power Dissipation at T <sub>C</sub> = 25°C	125	125	w
DM	Pulsed Drain Current <sup>2</sup>	108	108	Α

# Electrical Characteristics (T<sub>C</sub> = 25°C unless otherwise noted)

Symbol	Characteristic	Min	Max	Unit	Total Constitution
Off Chara	cteristics	<del></del>		- Oille	Test Conditions
V <sub>(BR)DSS</sub>	Drain Source Breakdown Voltage <sup>1</sup>		Τ	Tv	V0.V-1 050 4
	IRF140/142/540/542	100	<del>                                     </del>	┤ `	$V_{GS} = 0 \text{ V}, I_D = 250 \mu A$
	IRF141/143/541/543	60		1	
loss Zero Gate Voltage Dr	Zero Gate Voltage Drain Current		250	μΑ	V <sub>DS</sub> = Rated V <sub>DSS</sub> , V <sub>GS</sub> = 0 V
			1000	μΑ	V <sub>DS</sub> = 0.8 x Rated V <sub>DSS</sub> , V <sub>GS</sub> = 0 V, T <sub>C</sub> = 125°C
Igss Gate-Body Leaka	Gate-Body Leakage Current IRF140-143		± 100	nA	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V
	IRF540-543		± 500	1	
n Charact	teristics	· · · · · · · · · · · · · · · · · · ·	L	L	
V <sub>GS(th)</sub>	Gate Threshold Voltage	2.0	4.0	V	$I_D = 250 \ \mu A, \ V_{DS} = V_{GS}$
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	<u> </u>		Ω	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A
	IRF140/141/540/541		0.085		VGS - 10 V, ID = 15 A
	IRF142/143/542/543		0.11		
9fs	Forward Transconductance	6.0	<del></del>	S (U)	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 15 A

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Symbol	Characteristic	Min	Max	Unit	Test Conditions	
Dynamic C	characteristics					
Ciss	Input Capacitance		1600	pF	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V	
Coss	Output Capacitance		800	pF	f = 1.0 MHz	
C <sub>rss</sub>	Reverse Transfer Capacitance		300	pF	7	
Switching	Characteristics (T <sub>C</sub> = 25°C, Figures	1, 2,) <sup>3</sup>				
t <sub>d(on)</sub>	Turn-On Delay Time		30	ns	V <sub>DD</sub> = 45 V, I <sub>D</sub> = 15 A	
t <sub>r</sub>	Rise Time		60	ns	$V_{GS} = 10 \text{ V}, R_{GEN} = 4.7 \Omega$ $V_{GS} = 4.7 \Omega$	
t <sub>d(off)</sub>	Turn-Off Delay Time		80	ns	rigs - 4.7 80	
t <sub>f</sub>	Fall Time		30	ns		
t <sub>d(on)</sub>	Turn-On Delay Time		60	ns	V <sub>DD</sub> = 25 V, I <sub>D</sub> = 15 A	
t <sub>r</sub>	Rise Time		450	ns	$V_{GS} = 10 \text{ V}, R_{GEN} = 50 \Omega$ $R_{GS} = 50 \Omega$	
t <sub>d(off)</sub>	Turn-Off Delay Time		150	пѕ	11GS = 00 W	
t <sub>f</sub>	Fall Time		200	ns		
Qg	Total Gate Charge		60	пC	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 34 A V <sub>DD</sub> = 35 V	
Symbol	Characteristic	Тур	Max	Unit	Test Conditions	
Source-Dra	in Diode Characteristics		<del>'</del>	· · · · · · · · · · · · · · · · · · ·		
V <sub>SD</sub>	Diode Forward Voltage IRF140/141/540/541 IRF142/143/542/543	2.0 2.0	2.5 2.3	V V	I <sub>S</sub> = 27 A; V <sub>GS</sub> = 0 V I <sub>S</sub> = 24 A; V <sub>GS</sub> = 0 V	
t <sub>rr</sub>	Reverse Recovery Time	300		ns	$I_S = 4.0 \text{ A; } dI_S/dt = 25 \text{ A}/\mu S$	

- Notes
  1.  $T_J = +25^{\circ}\text{C}$  to  $+150^{\circ}\text{C}$ 2. Pulse width limited by  $T_J$ 3. Switching time measurements performed on LEM TR-58 test equipment.

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Typical Electrical Characteristics Figure 1 Switching Test Circuit

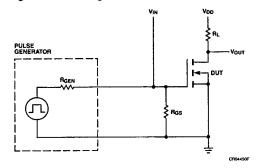
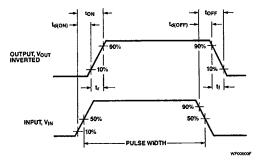


Figure 2 Switching Waveforms



### **Typical Performance Curves**

Figure 3 Output Characteristics

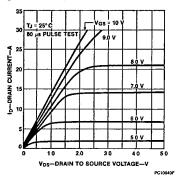


Figure 4 Static Drain to Source Resistance vs Drain Current

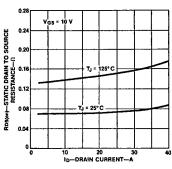


Figure 5 Transfer Characteristics

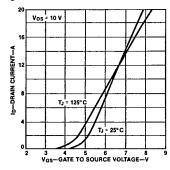
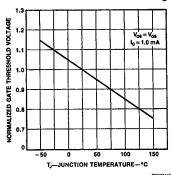


Figure 6 Temperature Variation of Gate to Source Threshold Voltage



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## Typical Performance Curves (Cont.)

Figure 7 Capacitance vs Drain to Source Voltage

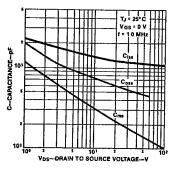


Figure 9 Forward Biased Safe Operating Area

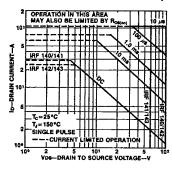


Figure 8 Gate to Source Voltage vs Total Gate Charge

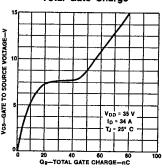


Figure 10 Transient Thermal Resistance vs Time

